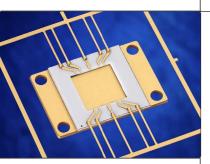


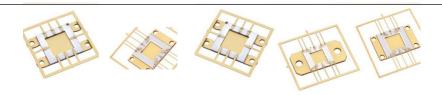
AND
HIGH SPEED
PACKAGING



- High thermal conductivity bases; many with bolt holes
- Low loss from DC to 23GHz
- Supplied with cup-shaped lid with epoxy preform
- Perfect for C, X, Ku and K band amplifiers
- One tuned specifically for Ka band (26—31 GHz)
- Leaded for easy assembly

BT Electronics 122 chemin de la cavée, 78630 Orgeval 01.69.18.16.60 contact@btelectronics.com

## LEADED AMPLIFIER PACKAGES

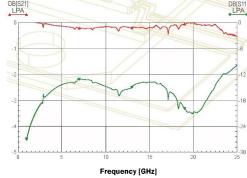


Designed originally for VSAT, the Strat-Edge LPA Series are ultra low loss leaded packages. Using a thermally conductive copper composite base, StratEdge engineers incorporated a patented microstrip-imbedded microstrip-microstrip transition on the alumina ceramic ring frame. The metal base and leads are attached to the ceramic with copper silver braze, a high temperature (> 600 deg C), high strength material that provides fantastic reliability. To protect the device, a plastic cup-shaped lid was designed to seal the package with a b-stage epoxy preform. LPA packages are then mounted into cutouts in the board where they are bolted in place and the leads attached with solder.

The LPA Series has exceptional wideband performance from DC to 23 GHz. Although initially targeted for VSAT networks, these amplifier packages are used for C, X, and other Ku band applications such as radar and point-to-point and point-to-multipoint radios. One package in the series is specially designed for Ka band, which is perfect for packaging devices used in the 26 to 31 GHz frequency range.

The result is the best performing line of leaded ceramic microwave packages ever introduced. The performance of these packages is so low loss and so consistent, they have become widely used for life cycle testing of compound semiconductors. The leaded construction provides easy and cost effective attachment to the next level of the system without sacrificing electrical performance so critical for high frequency performance.





PN	Outside Ceramic	Cavity Dimensions	Lid PN	I/0's	Cu-Composite Base
580274	.330" x .330"	.178" x .178"	200045	2RF, 8DC	2 Bolt holes
580286	.450" x .450"	.250" x .250"	200046	2RF, 8DC	4 Bolt holes
580293	.330" x .330"	.178" x .178"	200045	2RF, 2DC	2 Bolt holes
580341	.400" x .340"	.251" x .188"	200063	2RF, 8DC	2 Bolt holes
580348	.520" x .520"	.320" x .320"	200064	8RF	4 Bolt holes
580349	.450" x .450"	.250" x .250"	200046	2RF, 8DC	Earless
580350	.473" x .450"	.300" x .290"	200065	2RF, 8DC	Earless
580403 <sup>1</sup>	.450" x .450"	.250" x .250"	200046	2RF, 8DC	4 Bolt holes
580404	.450" x .450"	.260" x .250"	200046	2RF, 12DC	4 Bolt holes
580411	.260" x .215"	.128" x .080"	200078	2RF, 5DC	Earless
580450	.653" x .613"	.453" x .413"	200111	17RF	Earless

## 1 Tuned for Ka band

Other custom configurations available upon request. Please consult factory.

U.S. Patent#'s: 6,639,305; 6,271,579; 6,172,412; 5,448,826; 5,465,008, 5,692,298, 5,753,972; 5,736,783; 6,261,867; 09/054,049 & other patents pending Foreign Patent#'s: NI 091074; NI 118360; NI 186089; EP 0902976; AT 220245; AU 199724473; AU 199726655; AU 199918149; DE 69713771: EP 0902975; JP 2000510286; JP 2000510287; TW 322612; TW 4000590; TW 554451; WO 199743786; WO 199743787; WO 199934443; WO 2002063684 & other patents pending

